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CLAIMS

- 1. Optoelectronic connector comprising a package (1), an optical port (2), an electrical port (3), an optoelectronic/circuit positioned in this package and connected to these two ports, the optoelectronic circuit comprising a 5. bare control (5_7) and emission-detection (8) integrated circuit chip, an internal wall (29) of the package being provided with metallized connections (11), pads (10) of this integrated circuit being connected (12) directly to the metallized connections, characterized in that it comprises laser diodes (8) being transferred on the integrated dircuit, this connector constituting a basic unit link.
 - 2. Connector according to claim 1, characterized in that the laser diodes (8) are transferred (45) on the integrated circuit with a space (50) between these diodes equal to a space (21) between optical fiber terminations in the optical port/
 - 3. Connector according to one of the claims 1 to 2, characterized in that the package is an MID type package with connection metallizations deposited in a cavity of this package, contact armorings of the electrical port of this connector being formed by one of these metallizations.
 - 4. Connector according to claim 3, characterized in that the MID type package is made by means of a method with metallizations in two passes.
 - 5. Connector according to one of the claims 3 to 4, characterized in that the package is connected to the integrated circuit by BGA type connections, wire bonding or anisotropic film technology.
 - 6. Connector according to one of the claims 3 to 5, characterized in that the shielding of the package is of an MID type.
 - 7. Connector according to one of the claims 1 to 6, characterized in that pads (10) of the integrated circuit are connected (12) directly to the metallized connections.
 - 8. Conhector according to one of the claims 1 to 7, characterized in that the laser diodes are Vcsel diodes, preferably of the GaAs type.
 - 9. Connector according to one of the claims 1 to 8, characterized in that the optical port comprises an inclined mirror (19), preferably inclined at 45°.
 - 10. Connector according to one of the claims 1 to 9, characterized in

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that the optical port comprises a part (18) for positioning optical fiber terminations, this part abutting (23) a cant (24) of the integrated circuit.

- 11. Connector according to one of the claims 1 to 10, characterized in that the optical port comprises a limited access with two optical channels and in that the electrical port comprises contacts for electrical signals and contacts for a ground signal.
- 12. Connector according to one of the claims 1 to 11, characterized in that the package is a module and comprises means (27, 28) to be stacked on another package.
- 13. Connector according to one of the claims 1 to 12, characterized in that pads of the laser diodes are connected by connection wires directly to pads of the integrated circuit.
- 14. Connector according to one of the claims 1 to 13, characterized in that the optoelectronic circuit comprises means to carry out a conversion of the signals available at the optical port into signals available at the electrical port and/or vice versa.

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